May, 2003





# Technical Specification for Small Form Factor Pluggable (SFP)

SCP6811-GL-## (No Diagnostic Monitoring)

SCP6811-GL-##E (Diagnostic Monitoring with External Calibration)

	155.52Mbps		622.08Mbps		other	100M~155.52Mbps	
	Short Haul Intermediate Reach	V,	Long Haul Long Reach		other		
	Single 5.0 V		Single 3.3 V		other		
	1.3 µm		1.55 µm		other		
	W / Diagnostic Monitor		W/O Diagnostic Mon	itor			
Applicable P	art Numbers :						
	811-GL-AN_, SCP6811-GL-BN_, 8811-GL-AW_, SCP6811-GL-BW_						
	-		No Diagnostic Monitoring, Diagnostic Monitoring wih E	External	Calibrati	on,	
	Sumitomo Electric reserves the right to make changes in this specification without prior notice						

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**#Safety Precaution** Symbols This specification uses various picture symbols to prevent possible injury to operator or other persons or damage to properties for appropriate use of the product. The symbols and definitions are as shown below. Be sure to be familiar with these symbols before reading this specification.

$\triangle$	Warning	Wrong operation without following this instruction may lead to human death or serious injury.
$\triangle$	Caution	Wrong operation without following this instruction may lead to human injury or property damage.

Example of picture symbols

indicates prohibition of actions. Action details are explained thereafter.

indicates compulsory actions or instructions. Action details are explained thereafter.

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#### 1. General

Features and applications of SCP6811-GL are listed below.

#### Features

\* Multi Bit Rate Operation 100Mbps ~155.52Mbps \* Compliant with SFP MSA.(Alternative options available)

\* SFF-8472 rev.9 Compliant diagnostic monitoring inplemented.(SCP6811-GL-##E)

\* Power Supply Voltage Single +3.3V

\* Compact Package Size 56.5 X 13.7 X 8.6 mm

\* Electrical Interface AC coupled for DATA, LVTTL for Tx Disable, open collector output for

LOS and Tx Fault. Circuit ground is internally isolated from frame ground.

\* Fiber Coupled Power -5 ~ 0dBm \* Input Power Range -34 ~ -10dBm

\* Connector Interface LC Duplex Connector

\* Serial ID Functionality

\* Alarm and Warning Flags (SCP6811-GL-##E)

#### **Applications**

\*Telecommunications

- > SONET/LR, SDH/LH Application
- > ATM Application
- > Subscriber Loop
- > Metropolitan Area Network

# 2. Block Diagram

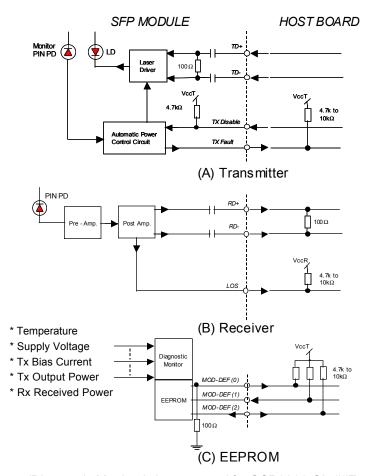


Figure 1. Block Diagram (Diagnostic Monitor is incorporated for SCP6811-GL-##E only.)

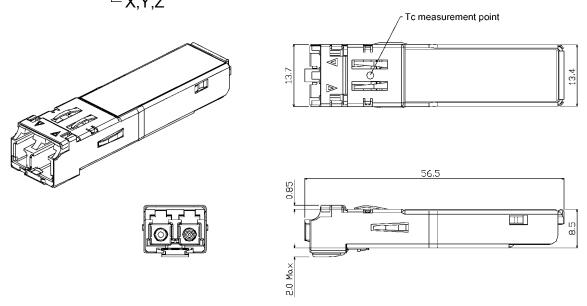


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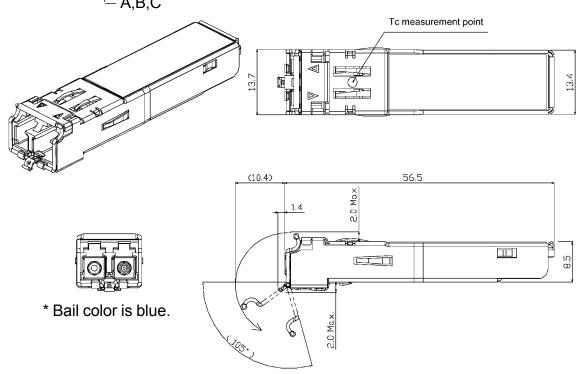
# 3. Package Dimensions

#### All dimensions are in mm.

3.1 SCP6811-GL- ☐#(E) ( MSA Standard Actuator Type ) \* Refer to P.20 for Part Number Information. -X,Y,Z



3.2 SCP6811-GL- ☐#(E) ( Bail Actuator Type ) \* Refer to P.20 for Part Number Information. A,B,C



\* Recommended Cage and Connector

-Top EMI Cage 1367035-1( Tyco/Electronics:1308292--AMP-04/00 ) -Bottom EMI Cage 1367034-1( Tyco/Electronics:1308292--AMP-04/00 ) -Host Connector

1367073-1( Tyco/Electronics:1308292--AMP-04/00 ) Please refer to their latest specifications.

Figure 2. Outline Dimensions

# 4. Pin Assignment

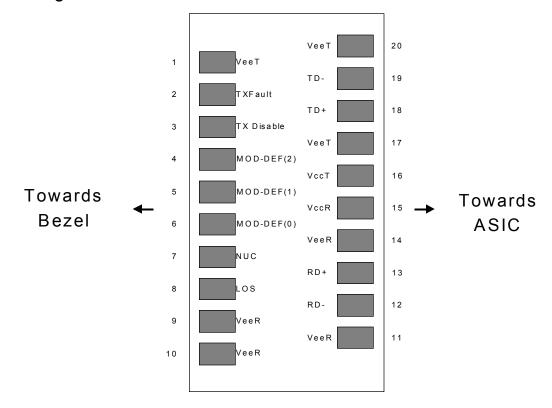


Figure 3. Diagram of Host Board Connector Block Pin Numbers and Names

Pin Num.	Name	Function	Plug Seq.	Notes
1	VeeT	Transmitter Ground	1	
2	TX Fault	Transmitter Fault	3	
		Indication		Note 1
3	TX Disable	Transmitter Disable	3	Note 2
				Module disables on high or open
4	MOD-DEF2	Module Definition 2	3	Note 3, 2 wire serial ID interface
5	MOD-DEF1	Module Definition 1	3	Note 3, 2 wire serial ID interface
6	MOD-DEF0	Module Definition 0	3	Note 3 Grounded internally via $100\Omega$
7	NUC	NUC	3	No User Connection,
				reserved for future function.
8	LOS	Loss of Signal	3	Note 4
9	VeeR	Receiver Ground	1	
10	VeeR	Receiver Ground	1	
11	VeeR	Receiver Ground	1	
12	RD-	Inv. Received Data Out	3	Note 5
13	RD+	Received Data Out	3	Note 5
14	VeeR	Receiver Ground	1	
15	VccR	Receiver Power	2	3.3V± 5%
16	VccT	Transmitter Power	2	3.3V± 5%
17	VeeT	Transmitter Ground	1	
18	TD+	Transmit Data In	3	Note 6
19	TD-	Inv. Transmit Data In	3	Note 6
20	VeeT	Transmitter Ground	1	

Plug Seq.: Pin engagement sequence during hot plugging.

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#### Note

1) Tx Fault is an open collector output that shall be pulled up with a  $4.7k - 10k\Omega$  resistor on the host board. Pull up voltage between 2.0V and VccT+0.3V. When high, output indicates a laser fault of some kind. Low indicates normal operation.

Tx Fault is asserted when bias current of laser exceeds the factory-calibrated threshold level.

- 2) Tx Disable is an input that is used to shut down the transmitter optical output. It is pulled up within the module with a  $4.7k\Omega$  resistor.
- 3) Mod-Def 0,1,2. These are the module definition pins. They should be pulled up with a  $4.7k 10k\Omega$  resistor on the host board. The pull-up voltage shall be VccT.

Mod-Def 0 indicates that the module is present

Mod-Def 1 is the clock line of two wire serial interface for serial ID

Mod-Def 2 is the data line of two wire serial interface for serial ID

- 4) LOS (Loss of Signal) is an open collector output that shall be pulled up with a 4.7k 10kΩ resistor. Pull up voltage between 2.0V and VccR+0.3V. Low indicates normal operation.
- 5) RD-/+: These are the differential receiver outputs. They are AC coupled  $100\Omega$  differential lines which should be terminated with  $100\Omega$  (differential) at the user SERDES. The AC coupling is done inside the module and is thus not required on the host board.
- 6) TD-/+: These are the differential transmitter inputs. They are AC-coupled, differential lines with  $100\Omega$  differential termination inside the module. The AC coupling is done inside the module and is thus not required on the host board.

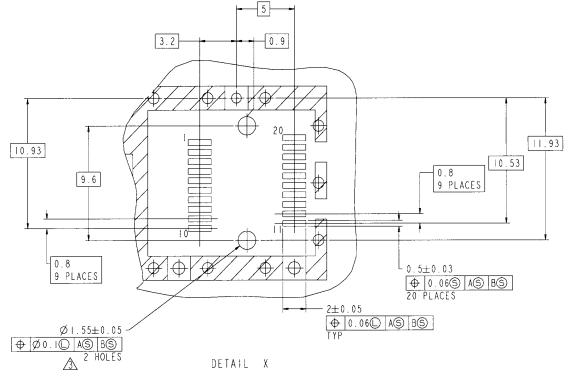


Figure 4. SFP Host Board Mechanical Layout

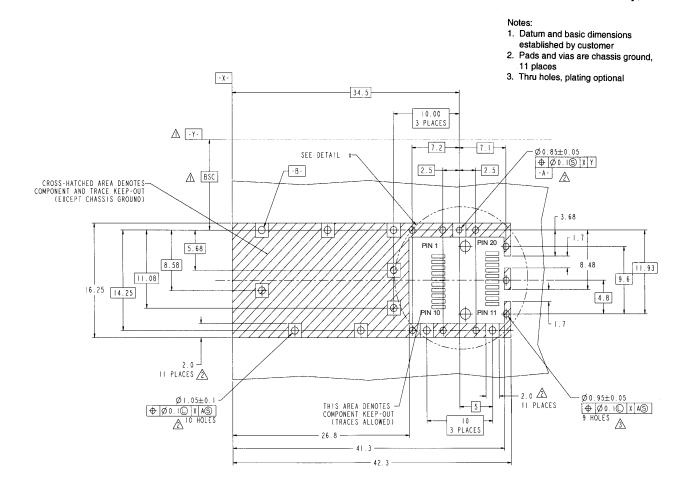
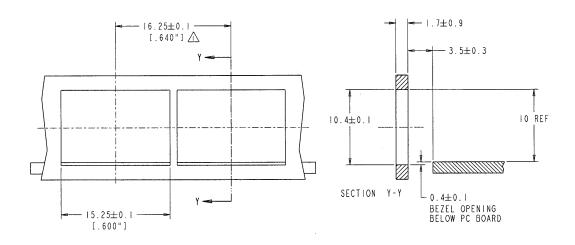


Figure 5. SFP Host Board Mechanical Layout (Cont.)



#### NOTES:

⚠ MINIMUM PITCH ILLUSTRATED, ENGLISH DIMENSIONS ARE FOR REFERENCE ONLY

2. NOT RECOMMENDED FOR PCI EXPANSION CARD APPLICATIONS

Figure 6. Recommended Bezel Design

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# 5. Absolute Maximum Ratings

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Storage Ambient Temperature	Ts	-40		85	°C	1
Operating Ambient Temperature	Tc	-5		70	°C	2
		-40		85		3
Optical Input Level	Pin			3.0	dBm	
Supply Voltage	VccT,R	0		4.0	V	
Input Voltage	Vi	0		VccT+0.3	V	4
Differential Input Voltage Sw ing (TD+,TD-)	Vin			2.5	Vp-p	

Notes

1. No condensation allowed. 2. SCP6811-GL-#N(E) 3. SCP6811-GL-#W(E) 4. For MOD-DEF (1:2), Tx Disable

# Marning

A

Use the product with the rated voltage described in the specification. If the voltage exceeds the maximum rating, overheating or fire may occur.

# 

Do not store the product in the area where temperature exceeds the maximum rating, where there is too much moisture or dampness, where there is acid gas or corrosive gas, or other extreme conditions. Otherwise, failure, overheating or fire may occur.

## 6. Electrical Interface

(Unless otherwise specified, VccT,R = 3.135 to 3.465 V and all operating temperature shall apply.)

#### 6-1. Operating Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply Voltage	VccT,R	3.135	3.30	3.465	V	
Power Dissipation	Pw			800	mW	1, 2
				1000		1, 3

Note

- 1. 155.52Mbps, PRBS 2^23-1, NRZ, 50% duty cycle data.
- 2. SCP6811-GL-#N(E) 3. SCP6811-GL-#W(E)

#### 6-2. Transmitter side

Parameter		Symbol	Min.	Тур.	Max.	Unit	Note
Differential Input Voltage Sw ing (TD+,TD-)		Vin	0.3		2.4	Vp-p	1
Input Differential Impedance		Zin	80	100	120	Ω	
Tx Fault	Fault	VfaultH	2.0		VccT+0.3	V	2, 3
	Normal	VfaultL	0		0.8	V	2, 3, 4
Tx Disable	Dis able	Vdi	2.0		VccT	V	5
	Enable	Vei	0		0.80	V	
Tdis Input Current	•	ldi	-1		50	μΑ	

Notes

- 1. Refer to Figure 7.
- Tx Fault is pulled up to VccT w ith a 4.7k 10kΩ resistor on the host board.
   When high, output indicates a laser fault of some kind. Low indicates normal operation.
- 3. Refer to P.10 about Tx Fault and Tx Shutdown behavior. 4. Sink Current: 1mA
- 5. Tx Disable input is internally terminated to VccT via 4.7 kΩ resistor. If pin3 is left open, Tx is disabled.

#### 6-3. Receiver side

Parameter		Symbol	Min.	Тур.	Max.	Unit	Note
Differential Output Voltage	Swing (RD+,RD-)	Vout	0.5		1.2	Vp-p	1
LOS	High	Vloh	2.0		VccR+0.3	V	2
Output Voltage	Low	VIol	0		0.8	V	2, 3
Data Rise / Fall Time		tr/tf			1.5	nsec	4

Notes

- 1. Vcc=+3.3V+/-5%, Output load resistance Rdif= $100\Omega$ . Refer to Figure1-(B). Refer to Figure7. about definition of differential swing.
- 2. LOS is pulled up to VccR with a 4.7k  $10k\Omega$  resistor on the host board. Low indicates normal operation.
- 3. Sink Current: 1mA
- 4. 20~80%,155.52Mbps, PRBS 2^23-1, NRZ, 50% duty cycle data.

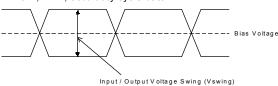


Figure 7. Definition of Differential Input / Output Voltage Swing

Differential Input / Output Voltage Swing (Vin / Vout) = 2 X Vswing

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#### 6-4. Module Definition

Parameter		Symbol	Min.	Тур.	Max.	Unit	Note
MOD_DEF(1:2)	High	Vih	0.7VccT		VccT+0.3	٧	1
Input Voltage	Low	Vil	0		0.3VccT	V	ı
MOD_DEF(2)	High	Voh	2.0		VccT	V	1
Output Voltage	Low	Vol1	0		0.4	V	1, 2

Notes

- 1. They shall be pulled up to VccT with a  $4.7k 10k\Omega$  resistor on the host board.
- 2. Sink Current: 3mA

# 7. Optical Interface

(Unless otherwise specified, VccT,R = 3.135 to 3.465 V and all operating temperature shall apply.)

#### 7-1. Transmitter side

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Average Output Power (Enable)	Po	-5.0		0	dBm	
Average Output Power (Disable)	Pdis			-45.0	dBm	
Extinction Ratio	Er	10			dB	1.0
Center Wavelength	λc	1263		1360	nm	1, 2
Spectral Width (-20dB Width)	Δλ			1.0	nm	
Side Mode Suppresion Ratio	SMSR	30			dB	
Eye Mask for Optical Output	Compli	ant with Telcor	dia GR-253 C	ORE and ITU-	-T G957	1
Jitter Generation	Tjpk			0.07	Ulp-p	3
	Tjrms			0.007	Ulrms	3

Note 1. Measured at 155.52Mbps, PRBS2^23-1, 50% duty cycle, NRZ.

Note 2. Measured at 100Mbps, PRBS2^7-1, 50% duty cycle, NRZ.

Note 3. SONET OC-3c data pattern filled with a PRBS 2^23-1 payload.

Measured with a bandpass filter having a high-pass cutoff freguency of 12kHz and a low-pass cutoff freguency of 1.3MHz.

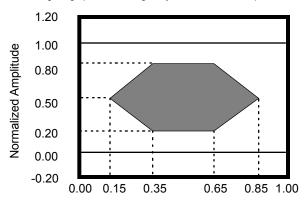


Figure 8. Optical Pulse Mask with Fourth Order Bessel-Thomson Filter Specified in ITU-T G.957

# **⚠** Warning

Do not look at the laser beam projection area (e.g. end of optical connector) with naked eyes or through optical equipment while the power is supplied to this product. Otherwise, your eyes may be injured.

#### 7-2. Receiver side

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Center Wavelength	-	1261		1580	nm	
Minimum Sensitivity	Pmin			-34.0	dBm	1, 2, 3
Overload	Pmax	-10.0			dBm	1, 2, 3
LOS Activation Level	P <sub>La</sub>	-45.0		-34.5	dBm	2, 3
LOS Deactivation Level	$P_{Ld}$	-44.5		-34.0	dBm	
LOS Hysteresis	Phys	0.5		6.0	dB	

Notes 1. BER=10^-10

2. Measured at 155.52Mbps, PRBS 2'23-1, NRZ

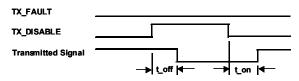
3. Measured at 100Mbps, PRBS 27-1, NRZ

## 7-3. Transceiver Timing Characteristics

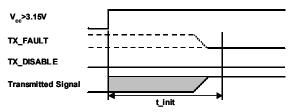
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Tx Disable Assert Time	t_off			10	us	1
Tx Disable Negate Time	t_on			1	ms	2
Time to Initialize	t_init			300	ms	3
Tx Fault Assert Time	t_fault			100	us	4
Tx Disable to Reset	t_reset	10			us	5
LOS Assert Time	t_loss_on	2.3		100	us	6
LOS Deassert Time	t_loss_off			100	us	7
Serial ID Clock Rate	f_serial_clock			100	kHz	

#### Notes

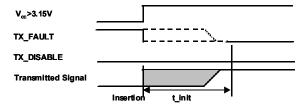
- 1. Time from rising edge of TX Disable to when the optical output falls below 10% of nominal.
- 2. Time from falling edge of TX Disable to when the modulated optical output rises above 90% of nominal.
- 3. From power on or negation of TX Fault using TX Disable.
- 4. Time from fault to TX fault on. 5. Time TX Disable must be held high to reset TX fault.
- 6. Time from LOS state to RX LOS assert. 7. Time from non-LOS state to RX LOS deassert.



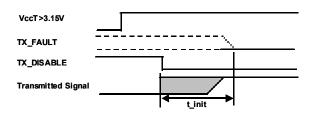
TX\_DISABLE timing during normal operation.



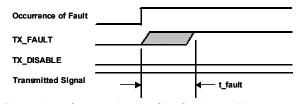
Power on initialization of SFP transceiver, TX\_DISABLE negated



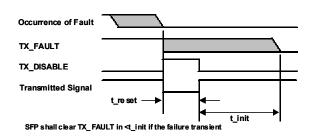
Example of initialization during hot plugging, TX\_DISABLE negated



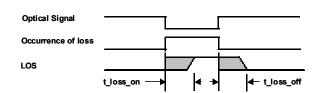
Power on initialization of SFP,TX\_DISABLE asserted



Detection of transmitter safety fault condition



Successful recovery from transient safety fault condition (Except for Type "B" and "Y". Refer to next page.)

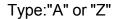


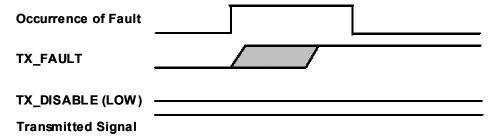
Timing of LOS detection

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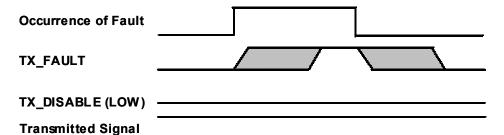
# 7-4. Tx\_Fault / Tx Shutdown Options

Type	Actuator	Tx Fault	Tx Shutdown on Tx Fault
Α	Bail	Latched	No
В	Bail	Not Latched	No
С	Bail	Latched	Yes
Х	MSA	Latched	Yes
Υ	MSA	Not Latched	No
Z	MSA	Latched	No





Type:"B" or "Y"



Type: "C" or "X"

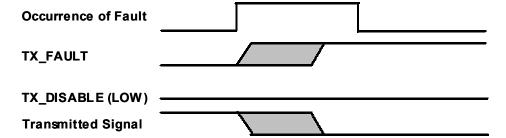


Figure 10. Part Number Identification For Tx\_Fault / Tx Shutdown Behavior

# 8. Digital Diagnostic Memory Map

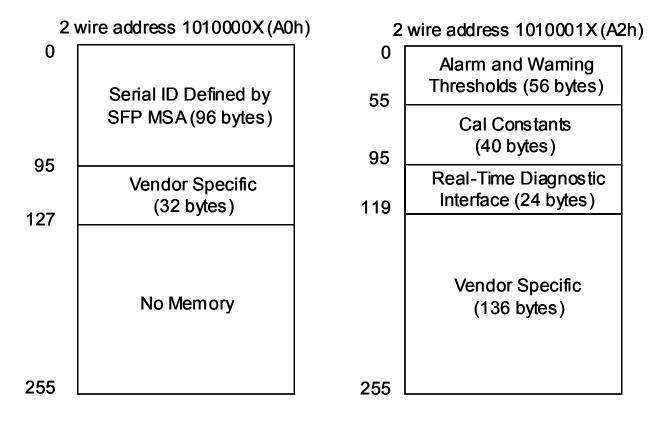


Figure 11. Digital Diagnostic Memory Map(A2h is applicable for SCP6811-GL-##E.)

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# 9. EEPROM Serial ID Memory Contents

The data can be read using the 2-wire serial CMOS EEPROM protocol of the Atmel AT24C01A or equivalent.

2 wire address 1010000X (A0h)

Address	Name of field	Hex	ASCII	Description
		BASE ID FIE	LDS	•
0	Identifier	03		SFP Transceiver
1	Ext. Identifier	04		
2	Connector	07		LC Connector
3		00		
4		10		OC-3 / LR-1
5	1	04		OC-3 / LR-1
6	<b>1</b>	00		
6 7	Transceiver	00		
8	1	00		
9	1	00		
10		00		
11	Encoding	05		SONET Scrambled
12	BR. Nominal	02		155.52Mbps
13	Reserved	00		100.021115 pc
14	Length(9um) - km	28		40km
15	Length (9um)	FF		401011
16	Length (50um)	00		
17		00		
	Length (62.5um)			
18 10	Length (Copper)	00		
19	Reserved	00	<u> </u>	
20	4	53	S	
21	4	75	u	
22	4	6D	m	
23	1	69	i	
24	1	74	t	
25		6F	0	
26		6D	m	
27		6F	0	
28	Vendor name	45	E	
29	1	6C	ī	
30	1	65	е	
31	1	63	С	
32	-	74	t	
33	-	72	r	
34	-	69	!	
35	4	63	С	
			C	
36	Reserved	00		
37	4	00		
38	Vendor OUI	00		
39		5F		
40		53	S	
41	_	43	С	
42	_	50	Р	
43		36	6	
44		38	8	
45		31	1	
46	1	31	1	
47	1	2D	ļ.	
48	Vendor PN	47	G	
<del>40</del> 49	V GIRGOI I IN	4C	L	
	1	2D	_	
50 51	1	41~43 , 58~5A	- A~C, X~Z	Astroday and To Contract
<u>51</u>	1			
52	-	4E or 57	N or W	Temperature range
53		45	E	Diagnostics(Ext.Cal)
	4	20		Non-diagnostics
54	4	20		
55		20		
56	Vendor rev	41~5A	A~Z	Variable
57		20		
		20		
		20		
58				
58 59	M/			4040
58 59 60	Wavelength	05		1310nm
58 59 60 61 62	- Wavelength Reserved			1310nm

Address	Name of field	Hex	ASCII	Description
64		ED ID FIELD	ıs I	1
65	Options	1A		
66	BR, max	00		
67	BR, min	00		
68				Year
69				Month
70	<u> </u>			
71	<u> </u>			
72	_			
73	4			
74	4			
75 70	Vendor SN	Note2		
76 77	4			
78	-			
79	-			
80	1			
81	1			
82	1			
83	1			
34				
85				
86				
87	Date code	Note3		
88	Date wde	Notes		
89				
90				
91				
92	Diagnostic Monitoring Type	58 (Note 4)		Diagnostics(Ext.Cal
		80		Non-diagnostics
93	Enhanced Options	B0(Note 4)	-	Diagnostics
	<u>'</u>	00		Non-diagnostics
94	SFF-8472 Compliance	01		Diagnostics Non-diagnostics
95	CC EVT	Note5		ivon-diagnostics
33	VENDOR SP		ELDS	l .
96	1	20		
97	1	20		
98	1	20		
99	1	20		
100	1	20		
101	1	20		
102	1	20		
103		20		
104		20		
105	_	20		
106	1	20		
107	1	20		
108	4	20		
109	4	20		1
110	4	20		ļ
111	Read-only	20	-	
112	4	20	-	
113	4	20		
114	4	20	-	
115	-	20	-	
116	1	20	<del>                                     </del>	1
117 118	-	20	-	+
	1	20	-	1
119 120	┨	20	-	+
120	┨	20 20	-	<del> </del>
	1		1	1
122 123	1	20 20	<del>                                     </del>	1
	†	20	1	1
		ILU	1	1
	1			
124 125 126	1	20 20		

Note1. Address 63 is check sum of bytes 0-62  $\,$  Note2. Aderess 68-83 Vendor Serial Number  $\,$ 

Note3. Aderess 84-91 Date code Note4. Refer to Section 10. (Enhanced Monitoring Function)

Note5. Address 95 is check sum of bytes 64-94

# 10. Enhanced Monitoring Functions (SCP6811-GL-##E)

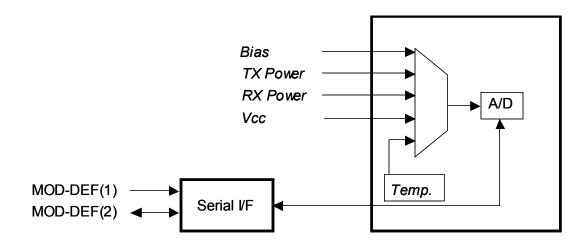


Figure 12. Block Diagram

Data Address	Bits	Description	Status(SEI)
92	7	Reserved for legacy diagnostic implementations. Must be '0' for compilance with SFF-8472.	0
92	6	Digital diagnostic monitoring implemented (described in SFF-8472). Must be '1' for compliance with SFF-8472.	1
92	5	Internally Calibrated	0
92	4	Externally Calibrated	1
92	3	Received power measurement type 0 = OMA, 1 = Average Power	1
92	2	Address change required. (Refer to SFF-8472)	0
92	1-0	Reserved	0

Enhanced Options, 2 wire address A0h

Data Address	Bits	Description	Status(SEI)
93	7	Optional Alarm/warning flags implemented for	1
		all monitored quantities	
93	6	Optional Soft TX_DISABLE control and	0
		monitoring implemented	
93	5	Optional Soft TX_FAULT monitoring	1
		implemented	
93	4	Optional Soft RX_LOS monitoring	1
		implemented	
93	3	Optional Soft RATE_SELECT control and	0
		monitoring implemented	
93	2-0	Reserved	0

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# 11. Calibration Calculation (SCP6811-GL-##E)

Calibration constants for External Calibration Option, 2 wire address A2h

Address	#Bytes	Name	Description	
56-59	4	$RP_{\!\scriptscriptstyle 4}$	Single precision floating-point calibration data for	
			received power. Byte 56 is MSB. Byte 59 is LSB.	
60-63	4	RP <sub>3</sub>	Single precision floating-point calibration data for	
		-	received power. Byte 60 is MSB. Byte 63 is LSB.	
64-67	4	$RP_2$	Single precision floating-point calibration data for	
		_	received power. Byte 64 is MSB. Byte 67 is LSB.	
68-71	4	$RP_1$	Single precision floating-point calibration data for	
		·	received power. Byte 68 is MSB. Byte 71 is LSB.	
72-75	4	$RP_0$	Single precision floating-point calibration data for	
		-	received power. Byte 72 is MSB. Byte 75 is LSB.	
76-77	2	I <sub>SLOPE</sub>	Unsigned fixed-point calibration data for laser bias	
			current. Byte 76 is MSB. Byte 77 is LSB.	
78-79	2	I <sub>OFFSET</sub>	16-bit signed 2's complement calibration data for laser	
			bias current. Byte 78 is MSB. Byte 79 is LSB.	
80-81	2	TP <sub>SLOPE</sub>	Unsigned fixed-point calibration data for laser output	
			power. Byte 80 is MSB. Byte 81 is LSB.	
82-83	2	TP <sub>OFFSET</sub>	16-bit signed 2's complement calibration data for laser	
			output power. Byte 82 is MSB. Byte 83 is LSB.	
84-85	2	T <sub>SLOPE</sub>	Unsigned fixed-point calibration data for transceiver	
			temperature. Byte 84 is MSB. Byte 85 is LSB.	
86-87	2	T <sub>OFFSET</sub>	16-bit signed 2's complement calibration data for	
			transceiver temperature. Byte 86 is MSB. Byte 87 is LSB.	
88-89	2	$V_{SLOPE}$	Unsigned fixed-point calibration data for supply voltage.	
			Byte 88 is MSB. Byte 89 is LSB.	
90-91	2	$V_{OFFSET}$	16-bit signed 2's complement calibration data for supply	
			voltage. Byte 90 is MSB. Byte 91 is LSB.	
92-94	3	Reserved		
95	1	Checksum		
			address bytes 0-94.	

Transceiver temperature: Temperature, T, is given by

$$T = T_{SLOPE} * T_{AD} + T_{OFFSET}$$

Where  $T_{AD}$  is 16-bit signed 2's complement A/D value at bytes 96-97,  $T_{SLOPE}$  is unsigned fixed-point value at bytes 84-85 and  $T_{OFFSET}$  is signed 2's complement value with LSB equal to 1/256 deg-C at bytes 86-87. The result, T, is 16-bit signed 2's complement value with LSB equal to 1/256 deg-C. The monitored output is the junction temperature of the diode inside the transceiver, hence, there is some discrepancy between the output and transceiver case temperature of the point illustrated in section 3 mechanical dimension.

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Supply voltage: Voltage, V, is given by

$$V = V_{SLOPE} * V_{AD} + V_{OFFSET}$$

Where  $V_{AD}$  is 16-bit unsigned A/D value at bytes 98-99,  $V_{SLOPE}$  is unsigned fixed-point value at bytes 88-89 and  $V_{OFFSET}$  is signed 2's complement value with LSB equal to 100  $\mu$ V at bytes 90-91. The result, V, is 16-bit unsigned value with LSB equal to 100  $\mu$ V.

#### Laser bias current: Current, I, is given by

$$| = |_{SLOPE} * |_{AD} + |_{OFFSET}$$

Where  $I_{AD}$  is 16-bit unsigned A/D value at bytes 100-101,  $I_{SLOPE}$  is unsigned fixed-point value at bytes 76-77 and  $I_{OFFSET}$  is signed 2's complement value with LSB equal to 2  $\mu$ A at bytes 78-79. The result, I, is 16-bit unsigned value with LSB equal to 2  $\mu$ A.

Laser output power: Power, TP, is given by

$$TP = TP_{SLOPE} * TP_{AD} + TP_{OFFSET}$$

Where TP<sub>AD</sub> is 16-bit unsigned A/D value at bytes 102-103, TP<sub>SLOPE</sub> is unsigned fixed-point value at bytes 80-81 and TP<sub>OFFSET</sub> is signed 2's complement value with LSB equal to 0.1  $\mu$ W atbytes 82-83. The result, TP, is 16-bit unsigned value with LSB equal to 0.1  $\mu$ W.

Received power: Power, RP, is given by

$$RP = RP_4 * RP_{AD}^4 + RP_3 * RP_{AD}^3 + RP_2 * RP_{AD}^2 + RP_1 * RP_{AD} + RP_0$$

Where RP<sub>AD</sub> is 16-bit unsigned A/D value at bytes 104-105 and RP<sub>4</sub>, RP<sub>3</sub>, RP<sub>2</sub>, RP<sub>1</sub> and RP<sub>0</sub> are single precision floating-point values at bytes 56-75. The result, RP, is 16-bit unsigned value with LSB equal to 0.1  $\mu$ W.

A/D Accuracy, 2 wire address A2h

Data Address	Parameter	Accuracy	Units Display	Note
96-97	Temperature	+/-3 deg-C	Signed 2's complement integer deg-C	Junction temperature of monitoring IC.
98-99	Vcc	+/-3%	x100µVolt	
100-101	TX Bias	+/-10%	x2µA	Specified by nominal value
102-103	TX Power	+/-3dB	x0.1µW	-5~0dBm
104-105	RX Power	+/-3dB (-34~-10dBm)	x0.1µW	At specified transmitter wavelength ( Section 7-1 )

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# 12. A/D Values and Status (SCP6811-GL-##E)

### Converted analog values, 2wire address A2h

Byte	Bit	Name	Description
96	All	Temperature MSB	Signed 2's complement integer temperature(-40 to
			+125C) Based on internal temperature measurement
97	All	Temperature LSB	Fractional part of temperature(count/256)
98	All	Vcc MSB	Internally measured supply voltage in transeciver.
99	All	Vcc LSB	Actual voltage is full 16 bit value *100uVolt.(Yields
			range of 0-6.55V)
100	All	TX Bias MSB	Measured Laser Bias Current in mA. Bias current is full
101	All	TX Bias LSB	16 bit value *2µA.(Full range of 0-131mA)
102	All	TX Power MSB	Measured TX output power in mW. TX power is full 16
103	All	TX Power LSB	bit value*0.1µW.(Full range of -40 to +8.2dBm)
104	All	RX Power MSB	Measured RX input power in mW. RX power is full 16
105	All	RX Power LSB	bit value*0.1µW.(Full range of -40 to+8.2dBm)
106-109	All	Reserved	

### Optional Status Bits, 2wire address A2h

Byte	Bit	Name	Description
110	0	Data_Ready_Bar	Indicates transceiver has achieved power up and data is
			ready. Bit remains high until data is ready to be read at
			which time the device sets the bit low.

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# 13. Alarm and Warning Flags (SCP6811-GL-##E)

# Alarm and Warning Flags, 2wire address A2h

Byte	Bit	Name	Description
112	7	Temp High Alarm	Set when internal temperature exceeds high alarm level.
112	6	Temp Low Alarm	Set when internal temperature is below low alarm level.
112	5	Vcc High Alarm	Set when internal supply voltage exceeds high alarm level.
112	4	Vcc Low Alarm	Set when internal supply voltage is below low alarm level.
112	3	TX Bias High Alarm	Set when TX Bias current exceeds high alarm level.
112	2	TX Bias Low Alarm	Set when TX Bias current is below low alarm level.
112	1	TX Power High Alarm	Set when TX output power exceeds high alarm level.
112	0	TX Power Low Alarm	Set when TX output power is below low alarm level.
113	7	RX Power High Alarm	Set when Received Power exceeds high alarm level.
113	6	RX Power Low Alarm	Set when Received Power is below low alarm level.
113	5-0	Reserved	
114	ΑII	Reserved	
115	ΑII	Reserved	
116	7	Temp High Warning	Set when internal temperature exceeds high warning level.
116	6	Temp Low Warning	Set when internal temperature is below low warning level.
116	5	Vcc High Warning	Set when internal supply voltage exceeds high warning level.
116	4	Vcc Low Warning	Set when internal supply voltage is below low warning level.
116	3	TX Bias High Warning	Set when TX Bias current exceeds high warning level.
116	2	TX Bias Low Warning	Set when TX Bias current is below low warning level.
116	1	TX Power High Warning	Set when TX output power exceeds high warning level.
116	0	TX Power Low Warning	Set when TX output power is below low warning level.
117	7	RX Power High Warning	Set when Received Power exceeds high warning level.
117	6	RX Power Low Warning	Set when Received Power is below low warning level.
117		Reserved	
118		Reserved	
119	All	Reserved	

# 14. Recommended Interface Circuit

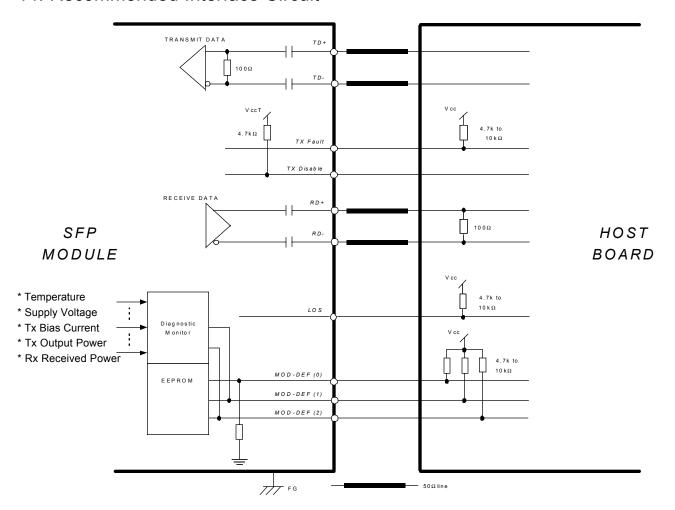


Figure 13. Recommended Interface Circuit (Diagnostic Monitor is incorporated for SCP6811-GL-##E only.)

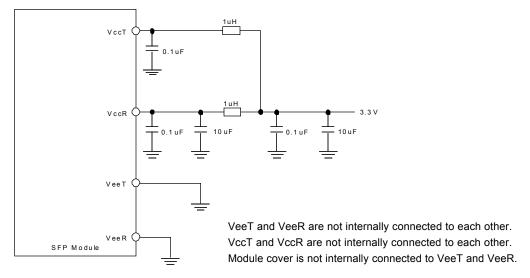


Figure 14. Recommended Supply Filtering Network

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# 15. Reliability Test Program

GR-468-CORE Issue 1, December 1998 Laser Module

HEADING	TEST	REFERENCE	CONDITIONS	SAM	IPLIN	G
				LTPD	SS	С
	Mechanical	MIL-STD-883	5 times/axis			
	Shock	Method 2002	1,500G, 0.5ms	20	11	0
Mechanical	Vibration	MIL-STD-883	Cond. A 20G, 20-2,000	20	11	0
Integrity		Method 2007	Hz, 4min/cy, 4cy/axis			
	Thermal Shock	MIL-STD-883	Delta T=100°C	20	11	0
		Method 1011	0°C to 100°C			
	Accel. Aging	(R)-4-53 Section	85°C; rated power			-
	(High Temp.)	5.18	1,000 hrs. for pass/fail	-	25	
			2,000, 5,000 hrs. for info.		10	
Endurance	Low Temp.	-	min. storage T	20	11	0
	Storage		1,000 hrs. for pass/fail			
			2,000 hrs. for info.			
	Temperature	Section 5.20	-40°C to +85°C			
	Cycling		500 for pass/fail	20	11	0
			1,000 for info.	-	11	-
	Damp Heat	MIL-STD-202	85°C/85%RH 1,000hrs.	20	11	0
		Method 103 or				
		IEC-60068-2-3				
	Cyc. Moist. Res.	Section 5.23	-	20	11	0
Special Tests	Internal	MIL-STD-883	Max. 5,000ppm water	20	11	0
	Moisture	Method 1018	vapour			
	ESD Threshold	Section 5.22		-	6	-

SS: Sample Size

C: Maximum number of failure allowed to pass the test.

# 16. Laser Safety

This product uses a semiconductor laser system and is a laser class 1 product acceptable FDA, complies with 21CFR 1040. 10 and 1040.11. Also this product is a laser class 1 product acceptable IEC 60825.

Class 1 Laser Product

## **∧** Caution

 $\mathcal{Q}$ 

If this product is used under conditions not recommended in the specification or this product is used with unauthorized revision, classfication for laser product safety standard is invalid. Classify the product again at your responsibility and take appropriate actions.

### 17. Other Precaution

Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed. The governmental approval is required to export this product to other countries. To dispose of these components, the appropriate procedure should be taken to prevent illegal exportation.

This module must be handled, used and disposed of according to your company's safe working practice.

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# 

Do not put this product or components of this product into your mouth. This product contains material harmful to health.

# ▲ Caution.

Dispose this product or equipment including this product properly as an industrial waste according to the regulations.

# 18. Ordering Information

SCP6811 - GL - a b c (LC Duplex Receptacle, Metallized)

Diagnostic Monitor / Calibration Type
Blank: No Diagnostic Monitoring

E:Diagnostic Monitoring with External Calibration

**Operating Ambient Temperature** 

N : Tc=-5~70°C W : Tc=-40~85°C

#### Actuator and Tx Fault Type

Туре	Actuator	Tx Fault	Tx Shutdown on Tx Fault	Part Number on Label
Α	Bail	Latched	No	SCP6811-GL-Abc
В	Bail	Not Latched	No	SCP6811-GL-Bbc
С	Bail	Latched	YES	SCP6811-GL-Cbc
Χ	MSA	Latched	YES	SCP6811-GL-Xbc
Υ	MSA	Not Latched	No	SCP6811-GL-Ybc
Z	MSA	Latched	No	SCP6811-GL-Zbc

### 19. For More Information

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